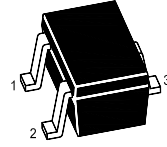
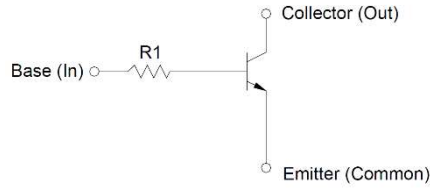


MMDTC150W

NPN Silicon Epitaxial Planar Digital Transistor

Features

- With built-in bias resistors
- Simplify circuit design
- Reduce a quantity of parts and manufacturing process



1.Base 2.Emitter 3.Collector
SOT-323 Plastic Package

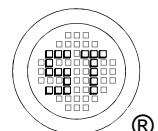
Absolute Maximum Ratings at $T_a = 25^\circ\text{C}$

Parameter	Symbol	Value	Unit
Collector Base Voltage	V_{CBO}	50	V
Collector Emitter Voltage	V_{CEO}	50	V
Emitter Base Voltage	V_{EBO}	5	V
Collector Current	I_{C}	100	mA

Thermal Characteristics

Parameter	Symbol	Max.	Unit
Total Power Dissipation	P_{tot}	200	mW
Thermal Resistance from Junction to Ambient ¹⁾	$R_{\theta\text{JA}}$	625	$^\circ\text{C/W}$
Operating Junction and Storage Temperature Range	$T_{\text{j}}, T_{\text{stg}}$	- 55 to + 150	$^\circ\text{C}$

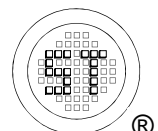
¹⁾ Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.



MMDTC150W

Characteristics at $T_a = 25^\circ\text{C}$

Parameter	Symbol	Min.	Typ.	Max.	Unit
DC Current Gain at $V_{CE} = 5\text{ V}$, $I_C = 1\text{ mA}$	h_{FE}	120	-	-	-
Collector Base Cutoff Current at $V_{CB} = 50\text{ V}$	I_{CBO}	-	-	100	nA
Collector Emitter Cutoff Current at $V_{CE} = 50\text{ V}$	I_{CEO}	-	-	100	nA
Emitter Base Cutoff Current at $V_{EB} = 5\text{ V}$	I_{EBO}	-	-	100	nA
Collector Base Breakdown Voltage at $I_C = 100\text{ }\mu\text{A}$	$V_{(BR)CBO}$	50	-	-	V
Collector Emitter Breakdown Voltage at $I_C = 100\text{ }\mu\text{A}$	$V_{(BR)CEO}$	50	-	-	V
Emitter Base Breakdown Voltage at $I_E = 10\text{ }\mu\text{A}$	$V_{(BR)EBO}$	5	-	-	V
Collector Emitter Saturation Voltage at $I_C = 10\text{ mA}$, $I_B = 0.5\text{ mA}$	$V_{CE(sat)}$	-	-	0.3	V
Transition frequency at $V_{CE} = 10\text{ V}$, $I_C = 5\text{ mA}$, $f = 100\text{ MHz}$	f_T	-	250	-	MHz
Input Resistor	R_1	70	100	130	K Ω



MMDTC150W

Electrical Characteristics Curves

Fig. 1 Output Characteristics Curve

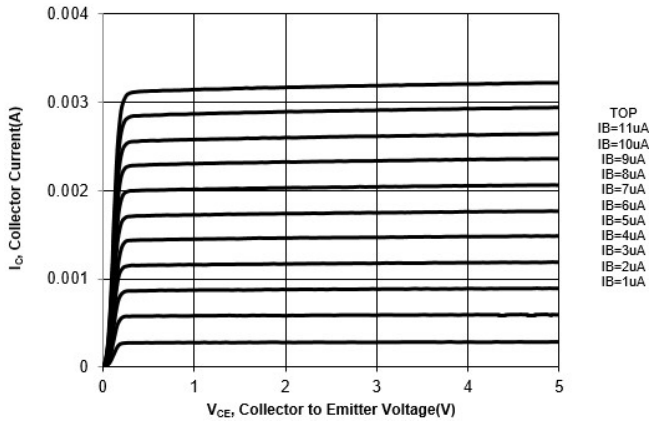


Fig. 2 Collector Current vs. V_{BE}

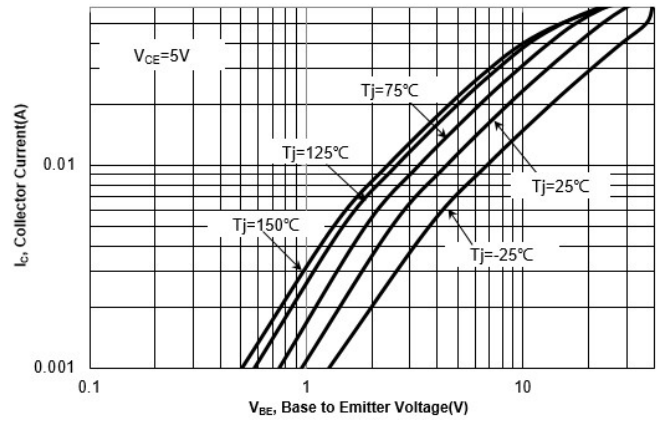


Fig. 3 h_{FE} vs. Collector Current

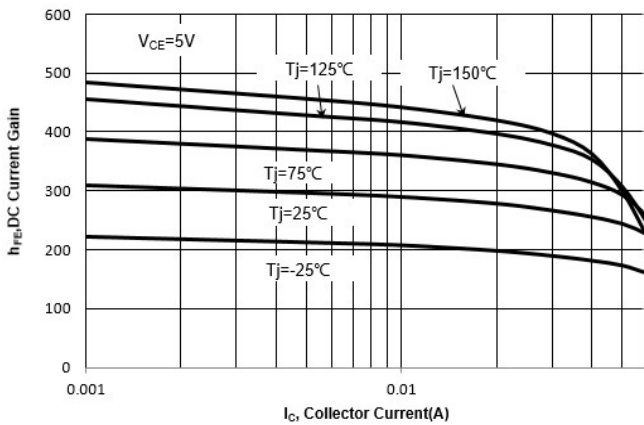


Fig. 4 $V_{CE(sat)}$ vs. Collector Current

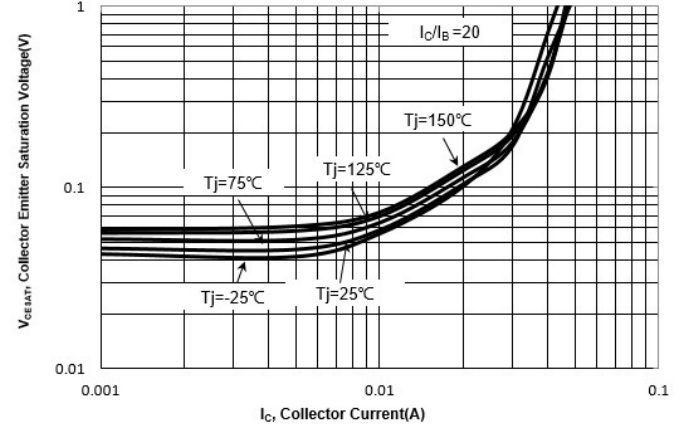
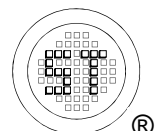
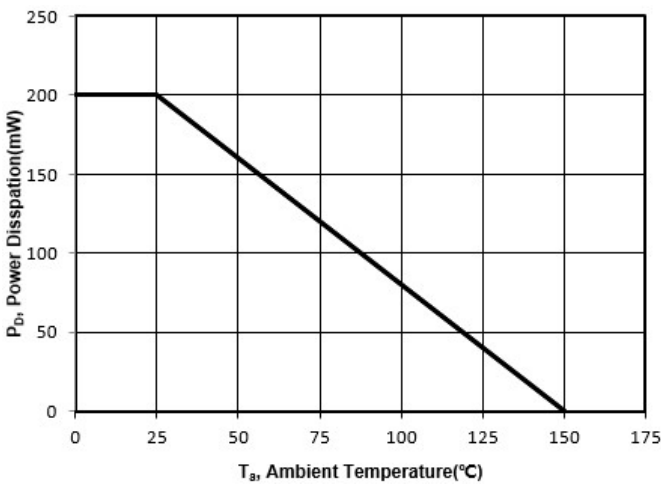


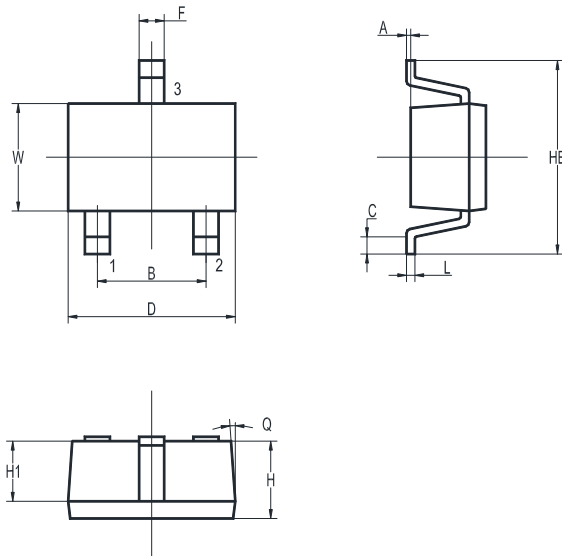
Fig. 5 Power Derating Curve



MMDTC150W

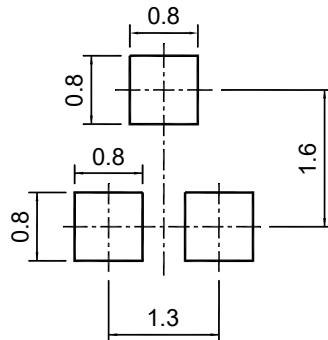
Package Outline Dimensions (Units: mm)

SOT-323



UNIT	A	B	C	D	H	H1	HE	F	L	W	Q
mm	0.1 MAX.	1.4 1.2	0.2 MIN.	2.1 1.9	1.0 0.8	0.7 TYP.	2.4 2.0	0.35 0.25	0.15 0.05	1.35 1.15	5° MAX.

Recommended Soldering Footprint



Packing information

Package	Tape Width (mm)	Pitch		Reel Size		Per Reel Packing Quantity
		mm	inch	mm	inch	
SOT-323	8	4 ± 0.1	0.157 ± 0.004	178	7	3,000

Marking information

- " RG " = Part No.
 - " YM " = Date Code Marking
 - " Y " = Year
 - " M " = Month
- Font type: Arial

